



ATTORNEY DOCKET 12636.001

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We hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) or § 365(c) of PCT international application(s) designating the United States of America listed below and on any attached continuation page and, insofar as the subject matter of each of the claims of this application is not disclosed in any such prior application in the manner provided by the first paragraph of Title 35, United States Code, § 112, we acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to us to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available between the filing date of such prior application and the national or PCT international filing date of this application:

<u>U.S. Patent No. 6,238,687</u> (application serial no.)	<u>5 April 1999</u> (filing date)	<u>Patented</u> (status - pending, patented or abandoned)
<u>U.S. Patent No. 5,912,225</u> (application serial no.)	<u>14 April 1997</u> (filing date)	<u>Patented</u> (status - pending, patented or abandoned)
<u>(application serial no.)</u>	<u>(filing date)</u>	<u>(status - pending, patented or abandoned)</u>

We hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

<u>(provisional application no.)</u>	<u>(filing date)</u>
<u>(provisional application no.)</u>	<u>(filing date)</u>

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We hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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